TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

TPC8002

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Small footprint due to small and thin package

• Low drain-source ON resistance : $RDS (ON) = 11.5 \text{ m}\Omega \text{ (typ.)}$

 $\bullet~$ High forward transfer admittance : $|\,Y_{fs}\,|\,$ = 15 S (typ.)

• Low leakage current : $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$

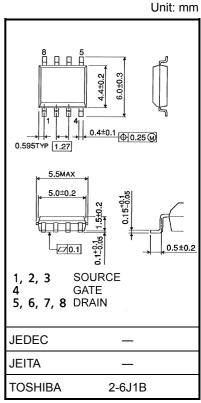
• Enhancement-mode : $V_{th} = 0.8 \sim 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	30	V	
Drain-gate voltage (F	R _{GS} = 20 kΩ)	V_{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	11	Α	
Diaili cuitelli	Pulse (Note 1)	I _{DP}	44		
Drain power dissipati	on (t = 10 s) (Note 2a)	P_{D}	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P_{D}	1.0	W	
Single pulse avalance	he energy (Note 3)	E _{AS}	157	mJ	
Avalanche current		I _{AR}	11	Α	
Repetitive avalanche (energy Note 2a) (Note 4)	E _{AR}	0.24	mJ	
Channel temperature	•	T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

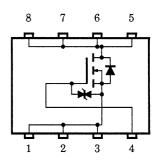
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

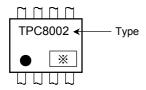
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

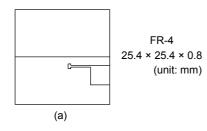
Marking (Note 5)

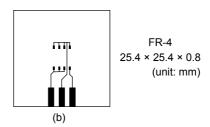


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 11 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature

Note 5: ● on lower left of the marking indicates Pin 1.

** shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

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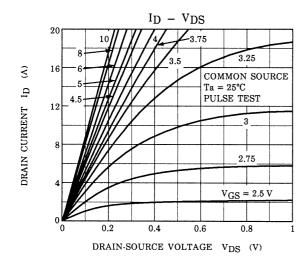
Electrical Characteristics (Ta = 25°C)

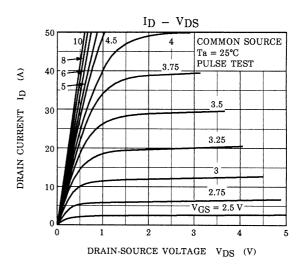
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	ı	_	10	μA
Drain-source br	Drain-source breakdown voltage		I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
Gate threshold v	oltage/	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source O	011		V _{GS} = 4 V, I _D = 5.5 A	_	19	22	mΩ
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 5.5 A	_	12	14	mΩ
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5.5 A	7.5	15	_	S
Input capacitance		C _{iss}		_	1425	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	200	_	
Output capacitance		Coss			790	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{\underset{0 \text{ V}}{\text{ V}}} \stackrel{I_{D} = 5.5 \text{ A}}{\underset{\text{RL} = }{\text{V}}} \stackrel{\text{O}}{\underset{\text{C}}{\text{V}}} \stackrel{\text{O}}{\underset{\text{T}}{\text{V}}} \stackrel{\text{O}}{\underset{\text{T}}} \stackrel{\text{O}}{\underset{\text{T}}{\text{V}}} \stackrel{\text{O}}{\underset{\text{T}}{\text{V}}} \stackrel{\text{O}}{\underset{\text{T}}} \text$	_	11	_	
	Turn-on time	t _{on}			19		ne
	Fall time	t _f		_	25	_	ns
	Turn-off time	t _{off}	Duty \leq 1%, $t_{\rm W} = 10 \mu \rm s$	_	100	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 11 A	_	44	_	
Gate-source charge		Q _{gs}		_	29	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	15	_	

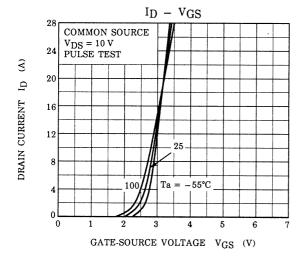
Source-Drain Ratings and Characteristics (Ta = 25°C)

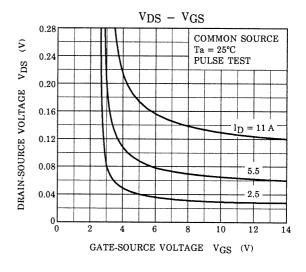
Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	44	Α
Forward voltage	(diode)	V _{DSF}	I _{DR} = 11 A, V _{GS} = 0 V	_	_	-1.2	V

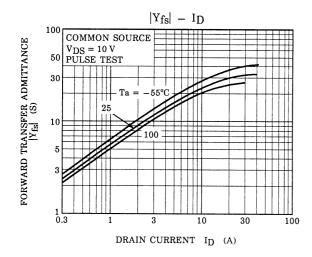
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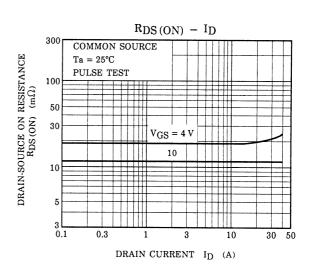




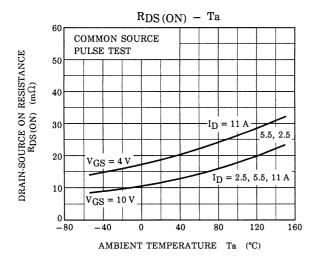


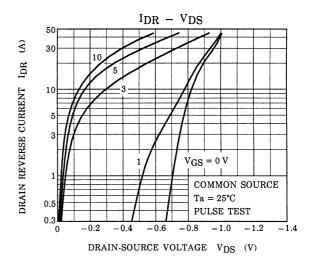


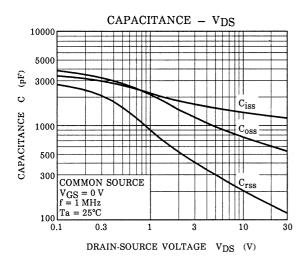


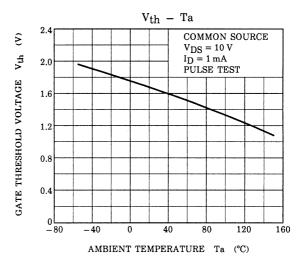


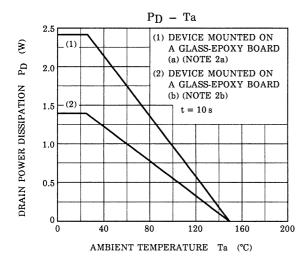
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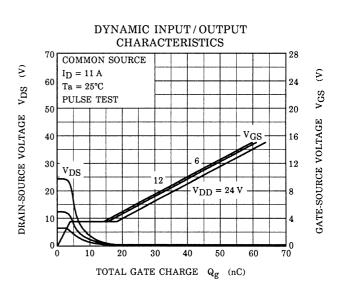




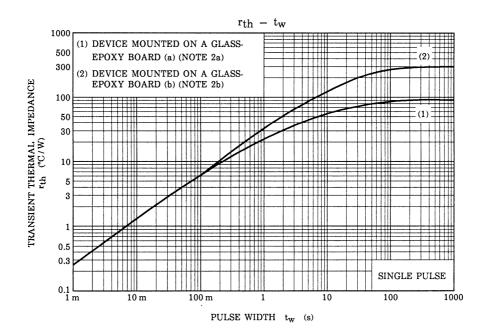


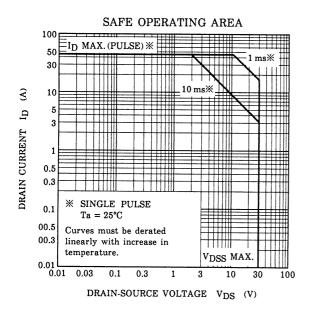


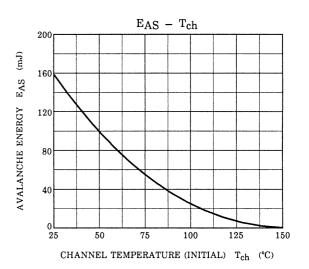


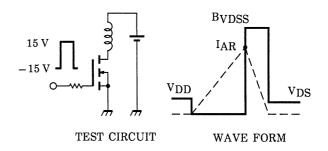


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$$\begin{array}{l} T_{ch} = 25^{\circ}\text{C (Initial)} \\ \text{Peak I}_{AR} = 11 \text{ A}, \; R_G = 25 \; \Omega \end{array} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot (\; \frac{B_{VDSS}}{B_{VDSS} - V_{DD}}) \\ V_{DD} = 24 \; \text{V}, \; L = 1.0 \; \text{mH} \end{array}$$

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